

April 2000

FQD16N15 / FQU16N15

150V N-Channel MOSFET

General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as audio amplifire, high efficiency switching for DC/DC converters, and DC motor control, uninterrupted power supply.

Features

- 11.8A, 150V, $R_{DS(on)}$ = 0.16 Ω @V_{GS} = 10 V Low gate charge (typical 23 nC)
- Low Crss (typical 30 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability



Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQD16N15 / FQU16N15	Units	
V _{DSS}	Drain-Source Voltage		150	V	
I _D	Drain Current - Continuous (T _C = 25°C)		11.8	Α	
	- Continuous (T _C = 100°C)		7.45	Α	
I _{DM}	Drain Current - Pulsed	(Note 1)	47.2	Α	
V _{GSS}	Gate-Source Voltage		± 25	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	230	mJ	
I _{AR}	Avalanche Current	(Note 1)	11.6	Α	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	5.5	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	6.0	V/ns	
P _D	Power Dissipation (T _A = 25°C) *		2.5	W	
	Power Dissipation (T _C = 25°C)		55	W	
	- Derate above 25°C		0.44	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		2.27	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		110	°C/W

^{*} When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	150			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.17		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 150 V, V _{GS} = 0 V			1	μΑ
		V _{DS} = 120 V, T _C = 125°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 25 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -25 V, V _{DS} = 0 V			-100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 5.9 A		0.123	0.16	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 5.9 A		8.5		S
C _{oss}	Output Capacitance Reverse Transfer Capacitance	f = 1.0 MHz		145 30	190 40	pF pF
C _{rss}	Reverse Transfer Capacitance			30	40	pF
Switchi	ing Characteristics					
$t_{d(on)}$	Turn-On Delay Time	V _{DD} = 75 V, I _D = 16.4 A,		11	30	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$		115	240	ns
$t_{d(off)}$	Turn-Off Delay Time	3		50	110	ns
t _f	Turn-Off Fall Time			80	170	ns
Q_g	Total Gate Charge	V _{DS} = 120 V, I _D = 16.4 A,		23	30	nC
Q_{gs}	Gate-Source Charge	V _{GS} = 10 V		4.5		nC
Q_{gd}	Gate-Drain Charge			11		nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Diode Forward Current				11.8	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				47.2	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 11.8 A			1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 16.4 A,		85		ns

- $\label{eq:Notes:1} \begin{tabular}{ll} \textbf{Notes:} \\ 1. & \textbf{Repetitive Rating: Pulse width limited by maximum junction temperature} \\ 2. & \textbf{L} = 2.75\text{mH, } \textbf{I}_{AS} = 11.8A, \ V_{DD} = 25\text{V}, \ \textbf{R}_{G} = 25\ \Omega, \ \textbf{Starting} \quad \textbf{T}_{J} = 25^{\circ}\text{C} \\ 3. & \textbf{I}_{SD} \leq 16.4A, \ d/dt \leq 300A/\mu s, \ V_{DD} \leq 8V_{DSS}, \ \textbf{Starting} \quad \textbf{T}_{J} = 25^{\circ}\text{C} \\ 4. & \textbf{Pulse Test: Pulse width} \leq 300\mu s, \ \textbf{Duty cycle} \leq 2\% \\ 5. & \textbf{Essentially independent of operating temperature} \end{tabular}$

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Typical Characteristics

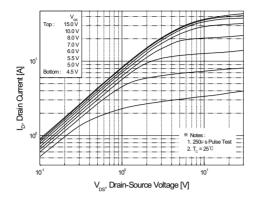


Figure 1. On-Region Characteristics

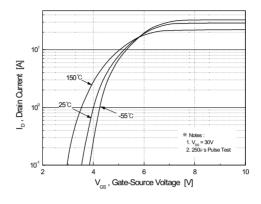


Figure 2. Transfer Characteristics

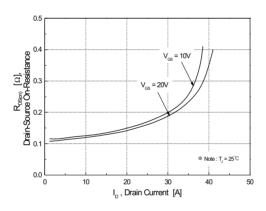


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

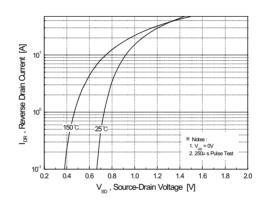


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

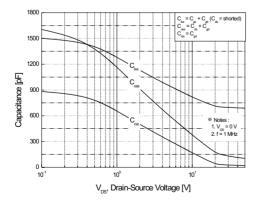


Figure 5. Capacitance Characteristics

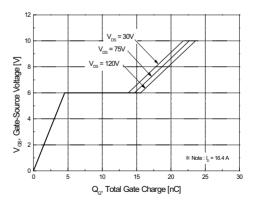


Figure 6. Gate Charge Characteristics

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Typical Characteristics (Continued)

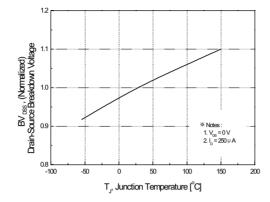


Figure 7. Breakdown Voltage Variation vs. Temperature

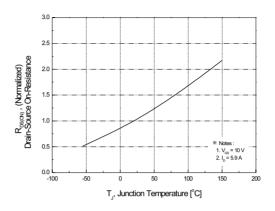


Figure 8. On-Resistance Variation vs. Temperature

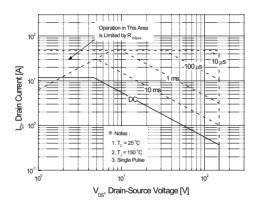


Figure 9. Maximum Safe Operating Area

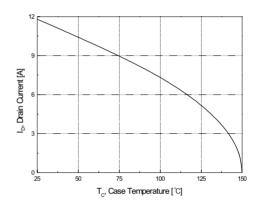


Figure 10. Maximum Drain Current vs. Case Temperature

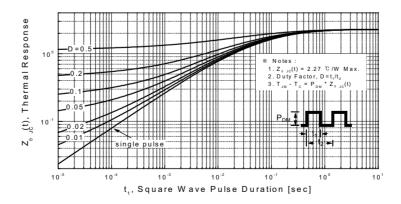
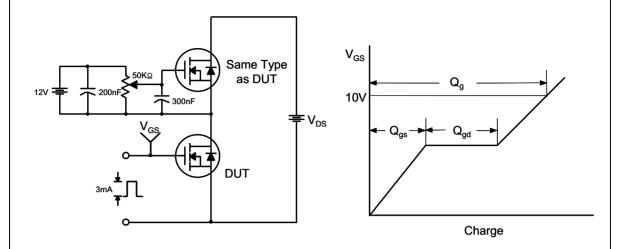


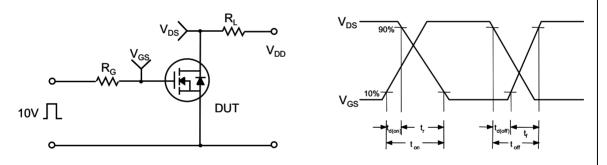
Figure 11. Transient Thermal Response Curve

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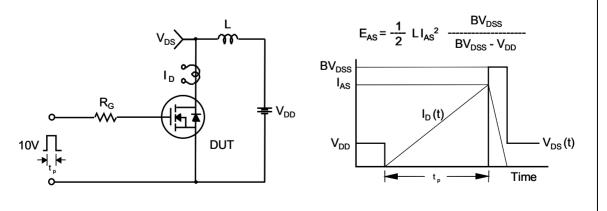
Gate Charge Test Circuit & Waveform



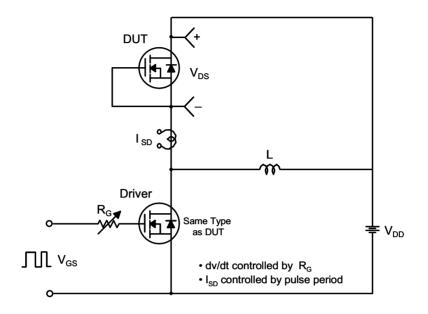
Resistive Switching Test Circuit & Waveforms

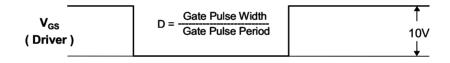


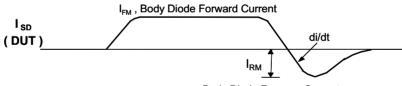
Unclamped Inductive Switching Test Circuit & Waveforms



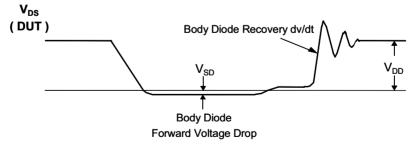
Peak Diode Recovery dv/dt Test Circuit & Waveforms



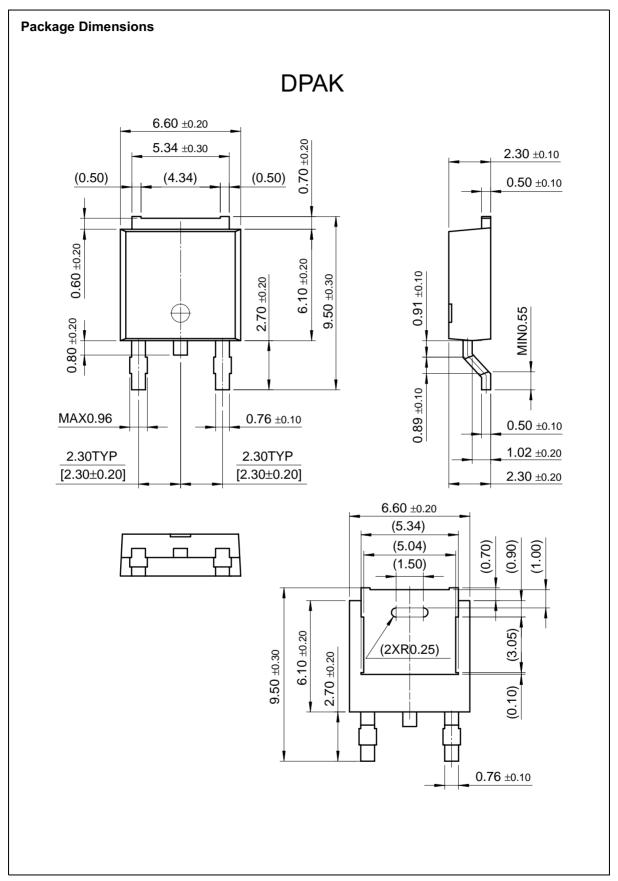


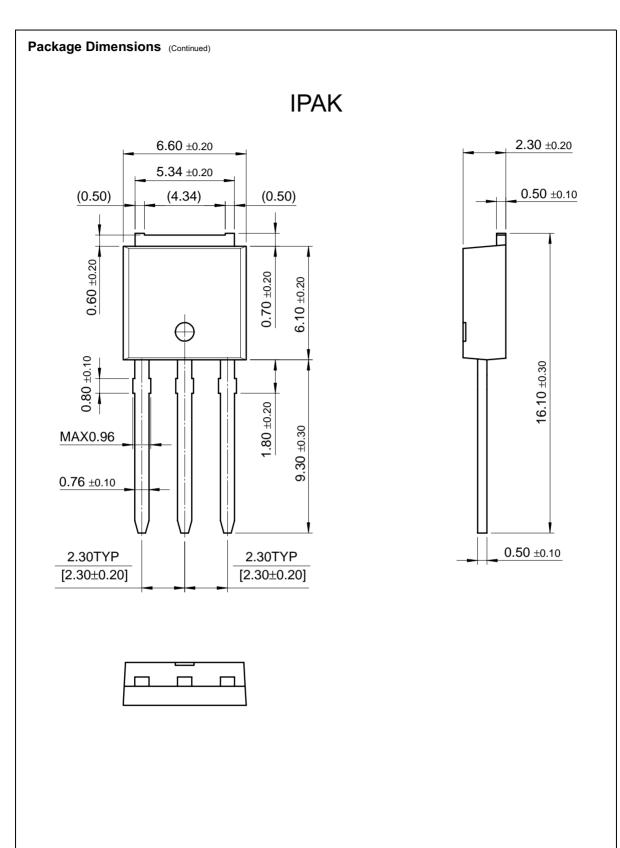


Body Diode Reverse Current



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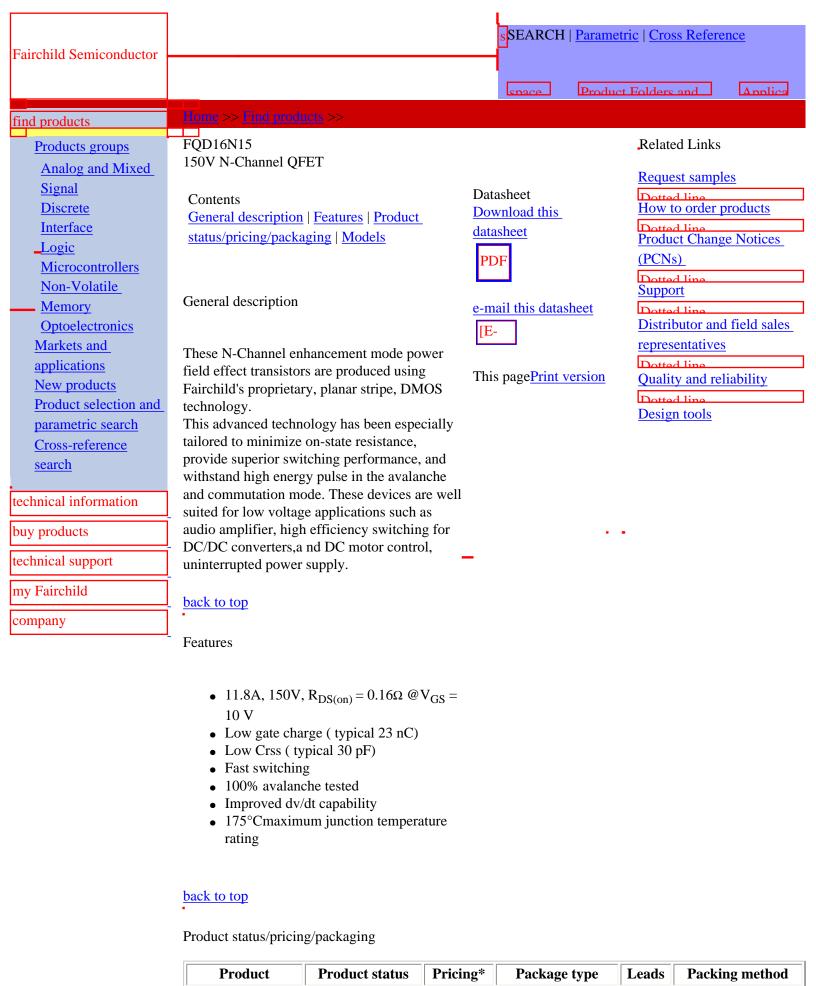
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FQD16N15TM	Full Production	\$0.58	TO-252(DPAK)	2	TAPE REEL

^{* 1,000} piece Budgetary Pricing

back to top

Models

Package & leads	Condition	Temperature range	Software version	Revision date
PSPICE				
TO-252(DPAK)-2	Electrical/Thermal	-55°C to 175°C	9	Oct 21, 2000

back to top

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